# Sumikon® EME-7720R

Epoxy; Epoxide

Sumitomo Bakelite Co., Ltd.

## Message:

Sumikon 7700-Series compounds are multi-functional-type molding compounds developed for overmolded BGA packages.

| General Information | | | |
|---|---|---|---|
| Features | Low hygroscopicity | | |
| Uses | Semiconductor molding compound | | |
| Forms | Liquid | | |
| Processing Method | Enclosure | | |
| **Physical** | **Nominal Value** | **Unit** | **Test Method** |
| Specific Gravity | 1.99 | g/cm³ | ASTM D792 |
| Water Absorption (24 hr) | 0.30 | % | ASTM D570 |
| **Mechanical** | **Nominal Value** | **Unit** | **Test Method** |
| Flexural Modulus (25°C) | 23100 | MPa | ASTM D790 |
| Flexural Strength (25°C) | 177 | MPa | ASTM D790 |
| **Thermal** | **Nominal Value** | **Unit** | **Test Method** |
| Glass Transition Temperature | 202 | °C | ASTM E1356 |
| Thermal Conductivity | 0.79 | W/m/K | ASTM C177 |
| **Electrical** | **Nominal Value** | **Unit** | **Test Method** |
| Volume Resistivity | 1.0E+13 | ohms·cm | ASTM D257 |
| **Thermoset** | **Nominal Value** | **Unit** | |
| Demold Time (175°C) | 0.50 - 1.7 | min | |
| Post Cure Time (175°C) | 2.0 - 8.0 | hr | |
| **Additional Information** | | | |

Spiral Flow, SB-U-03-003: 80 cmGel Time, SB-U-03-005, 175°C: 30 secThermal Expansion, SB-U-02-002, TTg: 4.1 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 44.1 MPaFlexural Modulus, SB-U-01-002, 240°C: 2650 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <1 ppmExtracted Cl-, SB-U-04-043: 5 ppmTransfer Pressure: 687-1177 MPa

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